

ABSTRACT

A fabricating method of a semiconductor integrated circuit device uses a mold which is provided with a plurality of air vents and movable pins which are formed such that the movable pins include grooves in distal ends thereof and project into the air vents. By clamping the mold in a state that the distal ends of the movable pins are pushed to a multi-cavity board at the time of clamping the mold, resin can be filled while leaking air inside the cavity through the grooves formed in the distal ends of the movable pins by setting the depths of the respective air vents to a fixed value irrespective of the irregularities of thicknesses of multi-cavity boards. Accordingly, it is possible to prevent the occurrence of insufficient filling of resin in the cavity, the occurrence of leaking of resin or defective welding whereby a yield rate of products can be enhanced.